



## 1.5A, 50V - 1000V Fast Recovery Surface Mount Rectifier

### FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

### APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Lighting application
- Snubber
- General purpose

### MECHANICAL DATA

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.060g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_F$	1.5	A
$V_{RRM}$	50 - 1000	V
$I_{FSM}$	50	A
$T_{J\ MAX}$	175	°C
Package	DO-214AC (SMA)	
Configuration	Single die	



**DO-214AC (SMA)**



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)										
PARAMETER	SYMBOL	RS 2AA	RS 2BA	RS 2DA	RS 2GA	RS 2JA	RS 2KA	RS 2MA	UNIT	
Marking code on the device		RS 2AA	RS 2BA	RS 2DA	RS 2GA	RS 2JA	RS 2KA	RS 2MA		
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V	
Reverse voltage, total rms value	$V_{R(RMS)}$	35	70	140	280	420	560	700	V	
Forward current	$I_F$	1.5								A
Peak forward surge current, 8.3ms single half sine wave superimposed on rated load	$I_{FSM}$	50								A
Junction temperature	$T_J$	- 55 to +175								°C
Storage temperature	$T_{STG}$	- 55 to +175								°C

## THERMAL PERFORMANCE

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	18	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	55	°C/W

## ELECTRICAL SPECIFICATIONS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 1.5\text{A}, T_J = 25^\circ\text{C}$	$V_F$	-	1.3	V
Reverse current @ rated $V_R$ <sup>(2)</sup>	$T_J = 25^\circ\text{C}$	$I_R$	-	5	$\mu\text{A}$
	$T_J = 125^\circ\text{C}$		-	200	$\mu\text{A}$
Junction capacitance	1MHz, $V_R = 4.0\text{V}$	$C_J$	50	-	pF
Reverse recovery time	$I_F = 0.5\text{A}, I_R = 1.0\text{A}, I_{rr} = 0.25\text{A}$	$t_{rr}$	-	150	ns
			-	250	ns
			-	500	ns

**Notes:**

1. Pulse test with  $PW = 0.3\text{ms}$
2. Pulse test with  $PW = 30\text{ms}$

## ORDERING INFORMATION

ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
RS2xA	DO-214AC (SMA)	7,500 / Tape & Reel

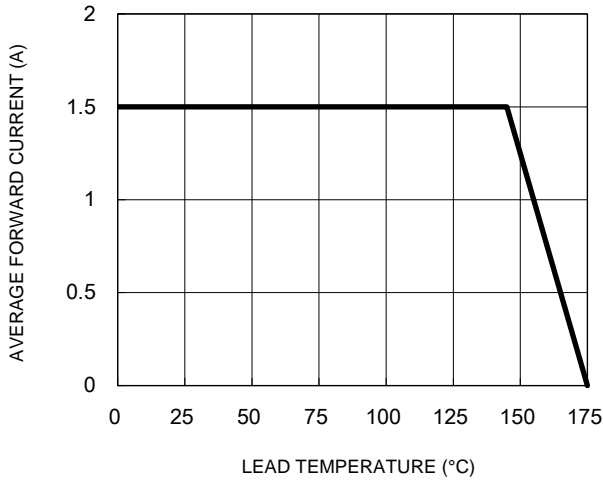
**Notes:**

1. "x" defines voltage from 50V(RS2AA) to 1000V(RS2MA)

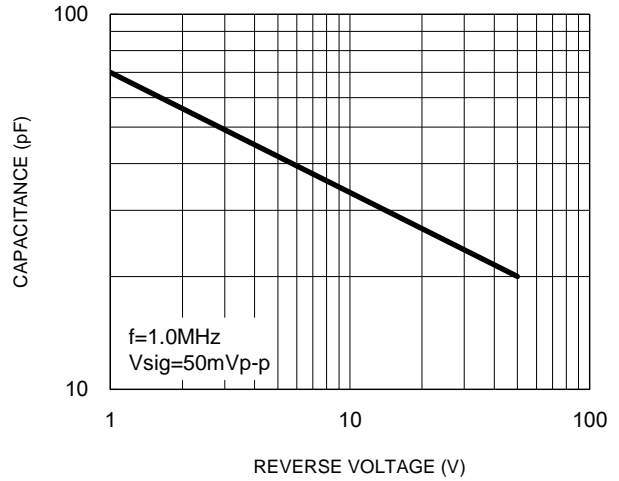
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

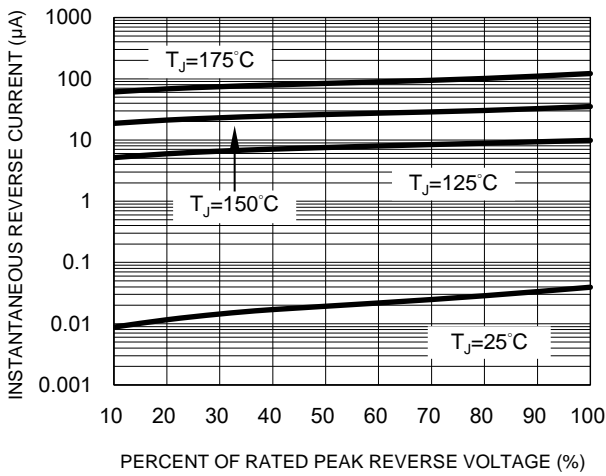
**Fig.1 Forward Current Derating Curve**



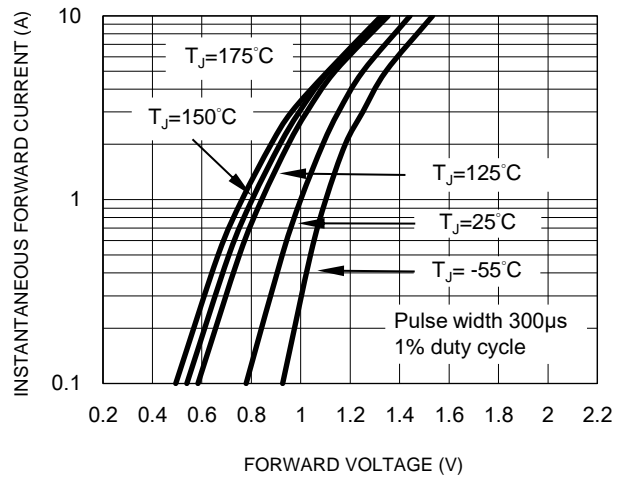
**Fig.2 Typical Junction Capacitance**



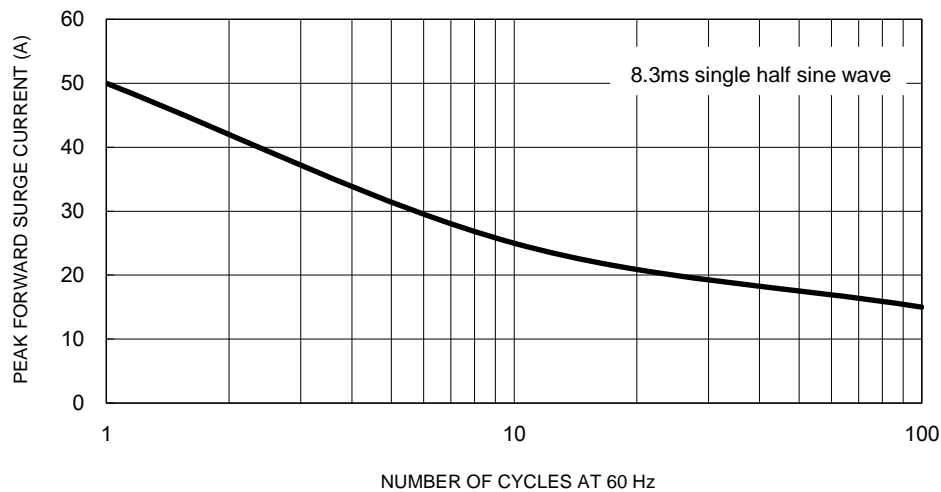
**Fig.3 Typical Reverse Characteristics**



**Fig.4 Typical Forward Characteristics**



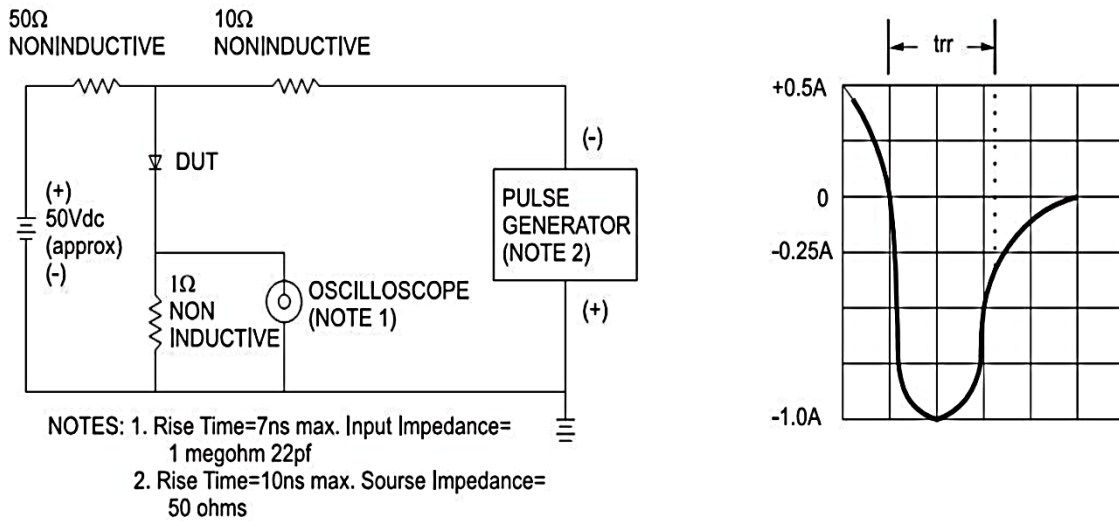
**Fig.5 Maximum Non-Repetitive Forward Surge Current**



**CHARACTERISTICS CURVES**

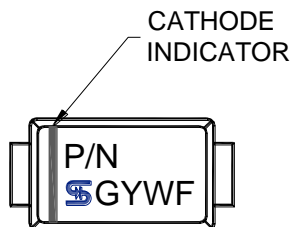
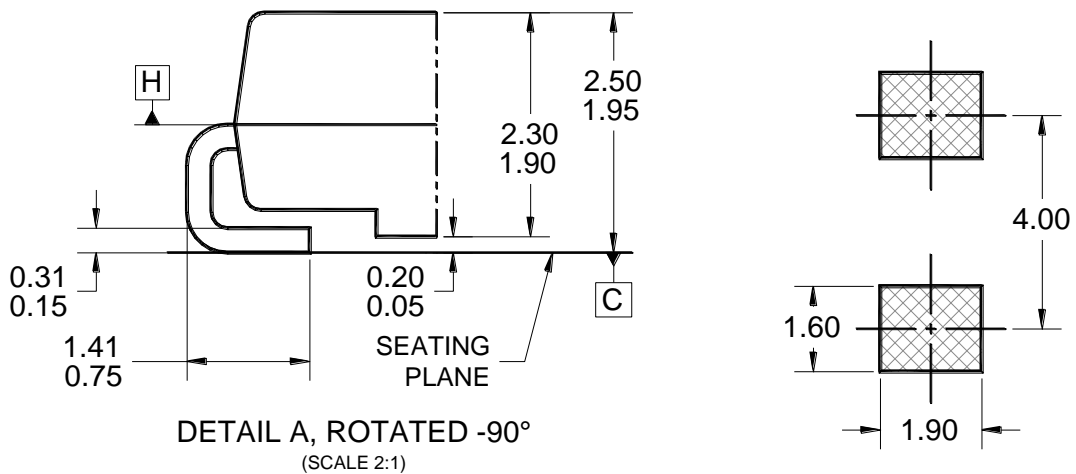
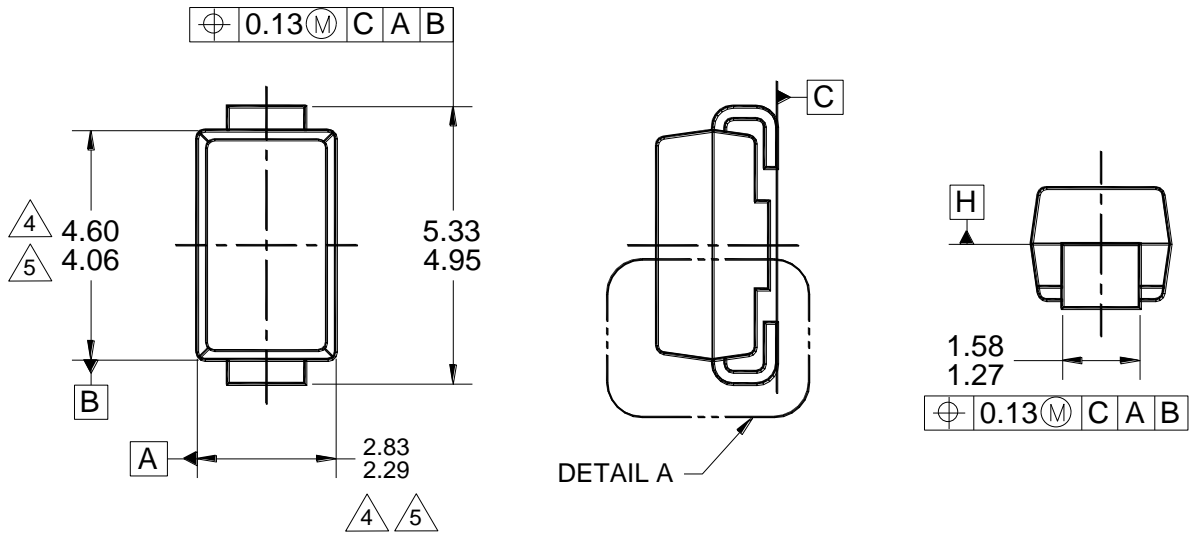
(T<sub>A</sub> = 25°C unless otherwise noted)

**Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram**



**PACKAGE OUTLINE DIMENSIONS**

**DO-214AC (SMA)**



**MARKING DIAGRAM**

P/N = MARKING CODE  
G = GREEN COMPOUND  
YW = DATE CODE  
F = FACTORY CODE

**NOTES: UNLESS OTHERWISE SPECIFIED**

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AC, ISSUE D.
4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
5. MOLDED PLASTIC BODY LATERAL DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.
6. DWG NO. REF: HQ2SD07-DO214SMC-034 REV A.

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